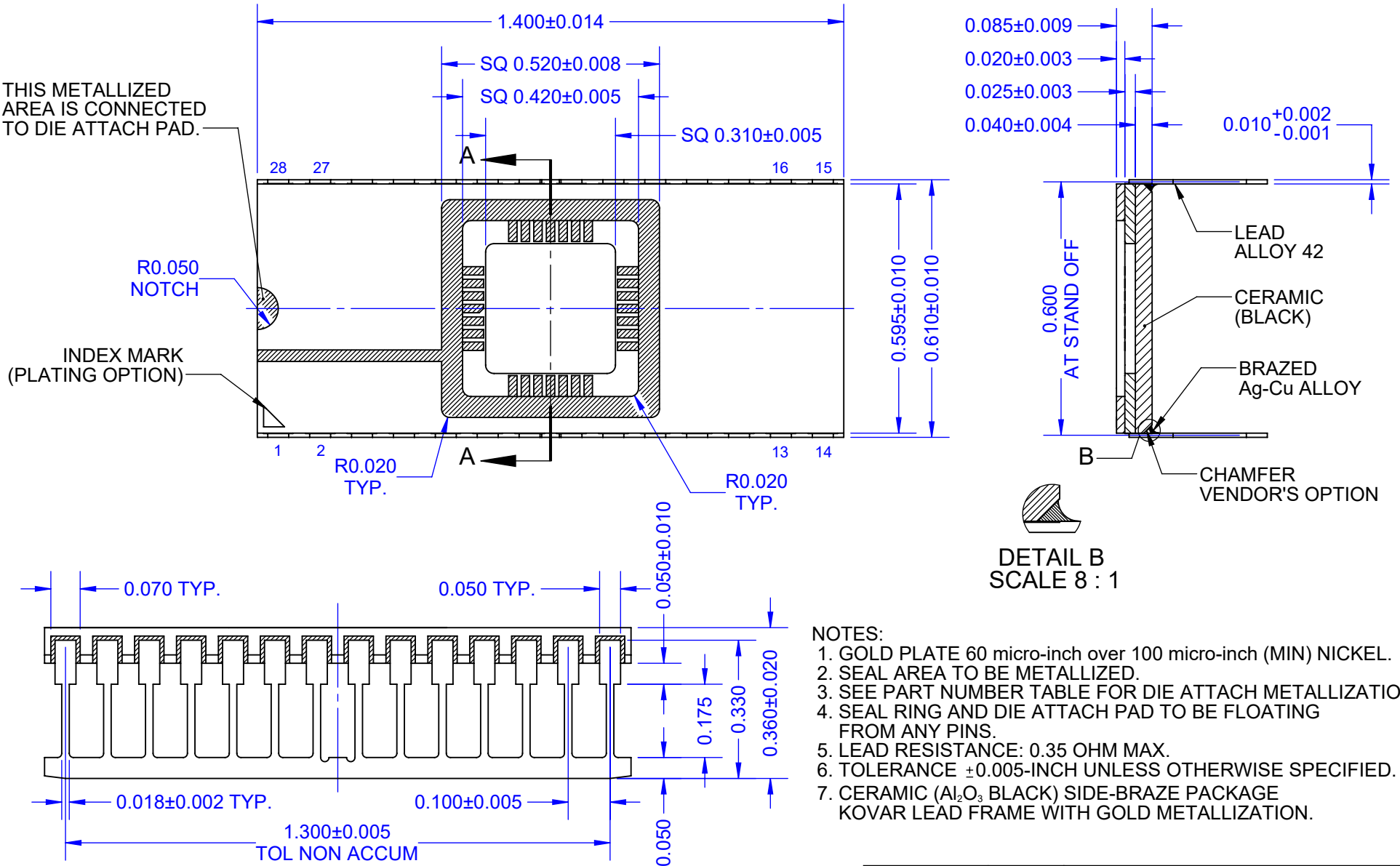


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD.



DETAIL B
SCALE 8 : 1

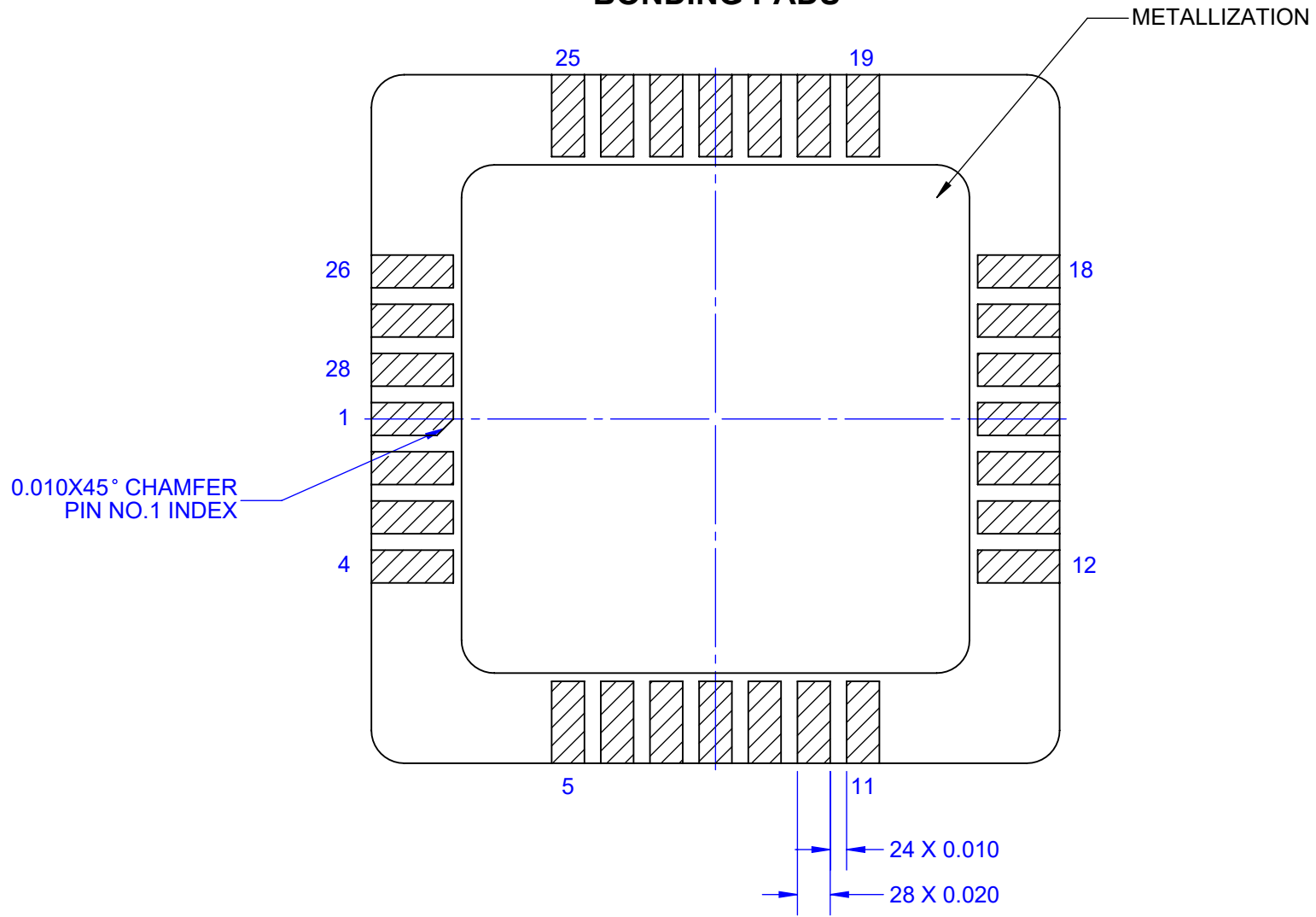
NOTES:

1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
2. SEAL AREA TO BE METALLIZED.
3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.35 OHM MAX.
6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP28F6-N310	GOLD	227180

APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	10/25/15				
ENG M. Hart	10/25/15	TITLE CERDIP28F6-N310 DIE PAD 310 MIL (7.8mm) SQ			
MFG		SCALE 3:1	SIZE A	DRAWING NO. 227180	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 3
CUST					
REVISED					

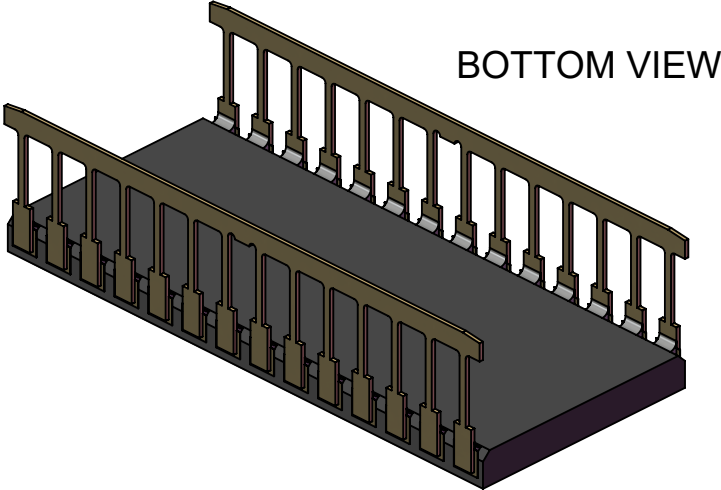
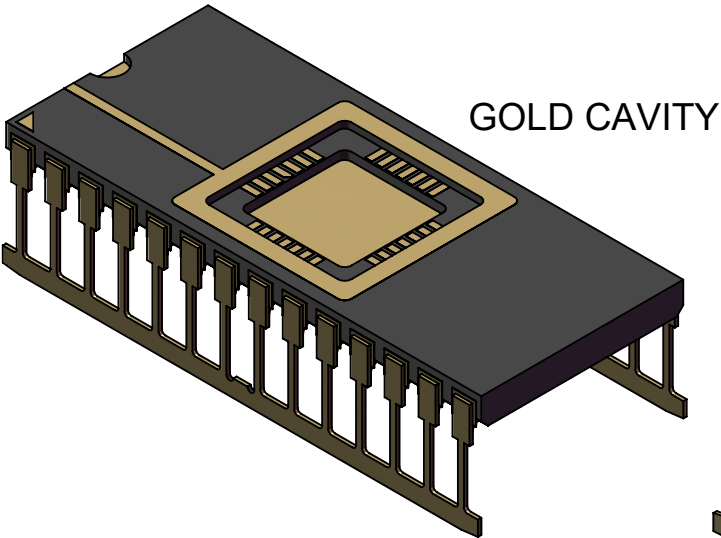
BONDING PADS



TITLE			
CERDIP28F6-N310 DIE PAD 310 MIL (7.8mm) SQ			
SCALE	SIZE	DRAWING NO.	REV
10:1	A	227180	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP28F6-N310	GOLD	227180

MODELS



PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP28F6-N310	GOLD	227180

TopLine[®]			
TITLE CERDIP28F6-N310 DIE PAD 310 MIL (7.8mm) SQ			
SCALE 2.5:1	SIZE A	DRAWING NO. 227180	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 3